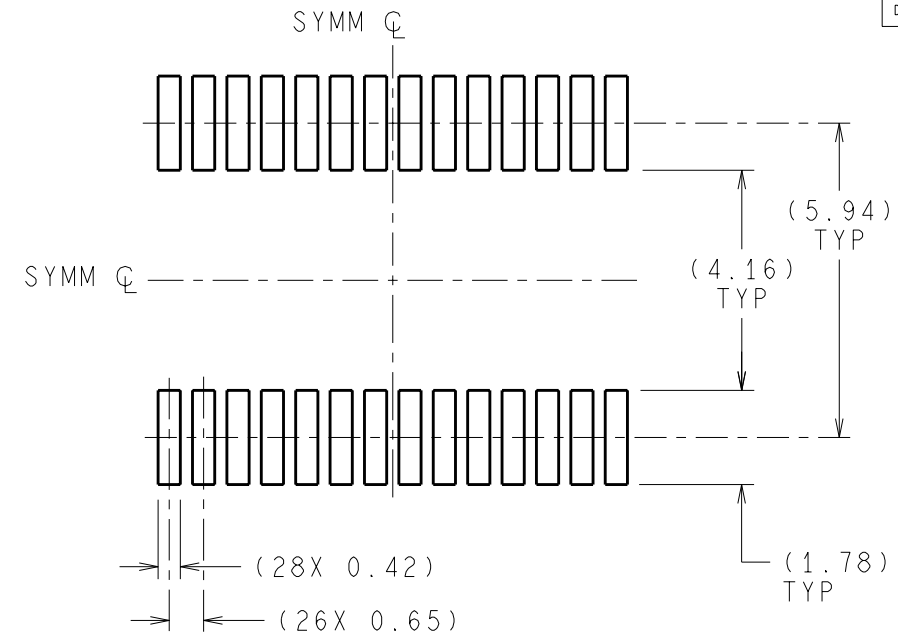
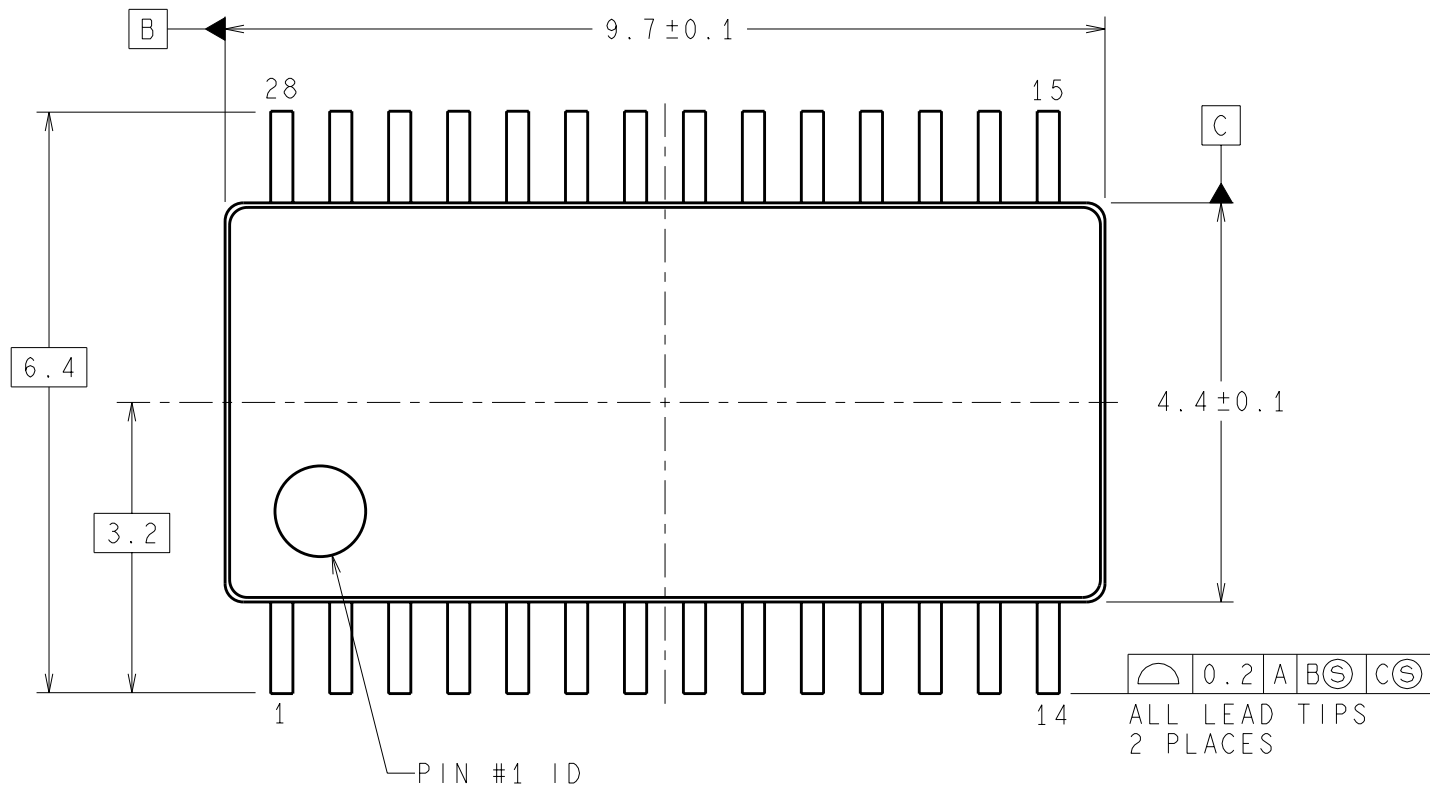
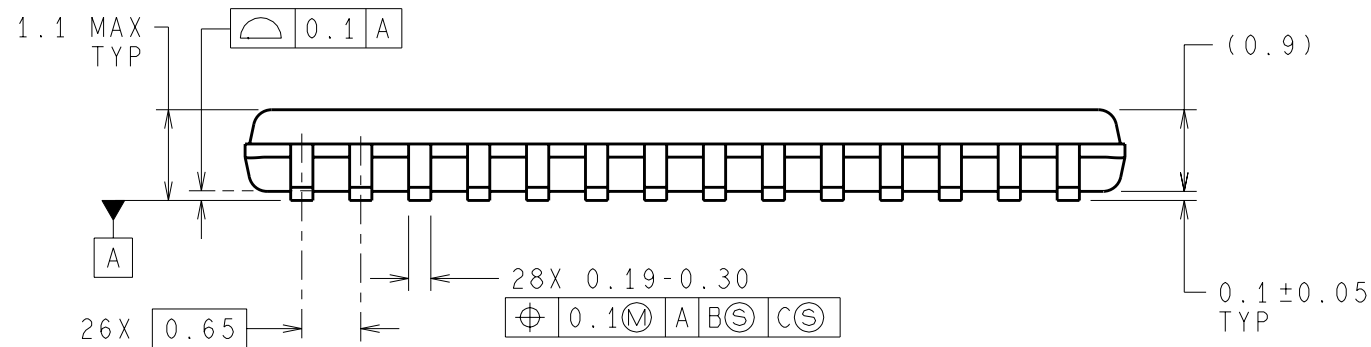


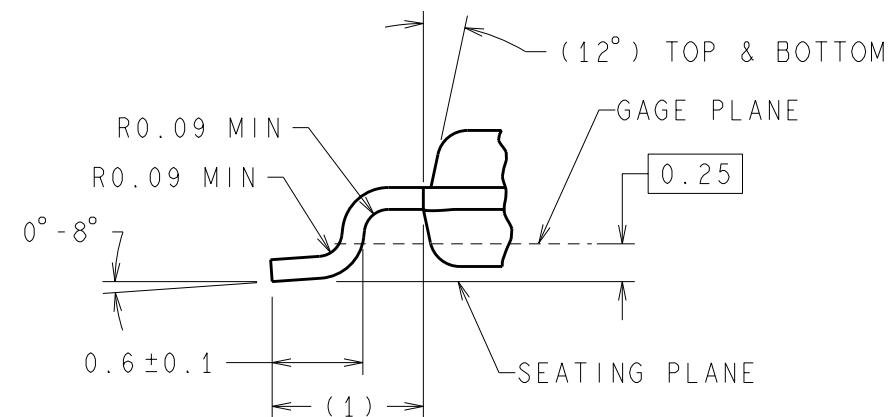
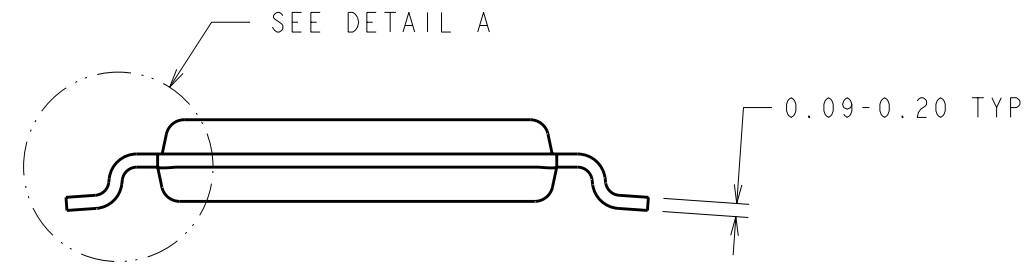
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11446	04/24/1996	MS/CS
B	LEAD POS. TOL. WAS 0.12; CHANGE DWG FORMAT TO B SIZE	782	08/29/2002	MS/RW
C	ADD LEAD FINISH NOTE & UPDATE TITLE.	976	03/26/2003	MS/RW
D	BODY WIDTH TOL. WAS ± 0.01 ; UPDATE LAND PATTERN DETAIL PER CURRENT STD'S.	1711	01/04/2005	MS/RW



LAND PATTERN RECOMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A
TYPICAL

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- REFERENCE JEDEC REGISTRATION MO-153, VARIATION AE.

APPROVALS		DATE	National Semiconductor	
DRAWN	MARTA SUCHY	04/24/1996	2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DFTG. CHK.	THANH LEQUANG	01/04/2005	MOLDED TSSOP, JEDEC, 9.7x4.4x0.9mm BODY, 28 LD, 0.65mm PITCH	
ENGR. CHK.	RANDALL WALBERG	01/04/2005		
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	NTS	B	(SC)MKT-MTC28	D
FORMERLY: N/A			SHEET 1 of 1	